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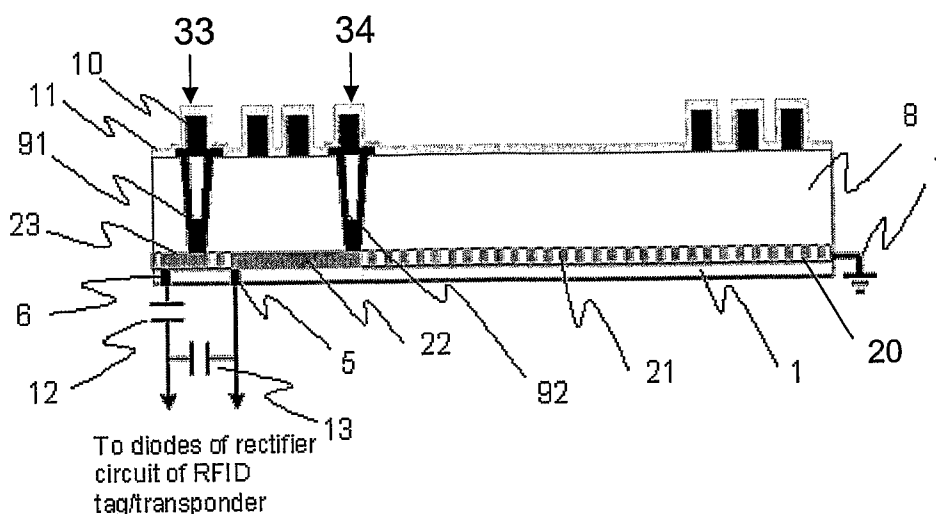
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(54) Title: AN ON-CHIP ANTENNA AND A METHOD OF FABRICATING THE SAME



(57) Abstract: An on-chip antenna fabricated on a chip for wireless communication is disclosed. The on-chip antenna includes a first dielectric layer arranged on a surface of the chip of the radio frequency identification tag, a grounded shielding layer arranged on the first dielectric layer, a second dielectric layer arranged on the grounded shielding layer, and a planar antenna arranged on the second dielectric layer above the grounded shielding layer. A radio frequency identification tag with an on-chip antenna and a method of fabricating an on-chip antenna on a chip for wireless communication are also disclosed.

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